

**描述 / Descriptions**

快恢复二极管，反向电压：50V~1000V，正向电流：3.0A，薄型 SMAF 封装。

Surface Mount Fast Recovery Rectifiers, Reverse Voltage : 50 to1000V,Forward Current:3.0A ,SMAF thin package.

**特征 / Features**

玻璃钝化芯片，反向恢复时间快，无铅符合欧盟 RoHS 指令 2011/65/EU，适用表面贴装。无卤产品。

Glass Passivated Chip Junction, Fast reverse recovery time, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications. Halogen free product.

**用途 / Applications**

一般用途.

General purpose.

**内部等效电路 / Equivalent Circuit**

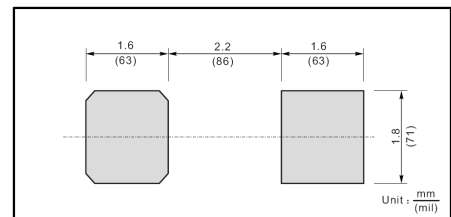


**引脚排列 / Pinning**



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



**印章代码 / Marking**

见印章说明。See Marking Instructions.

**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating							单位 Unit
		RS3AF	RS3BF	RS3DF	RS3GF	RS3JF	RS3KF	RS3MF	
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_c = 125^\circ\text{C}$	$I_{F(AV)}$	3.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	$I_{FSM}$	100							A
Typical Junction Capacitance at $V_R=4\text{V}$ $f=1\text{MHz}$	$C_j$	45							pF
Typical Thermal Resistance <sup>1)</sup>	$R_{\theta JA}$	50							$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55~+150							$^\circ\text{C}$

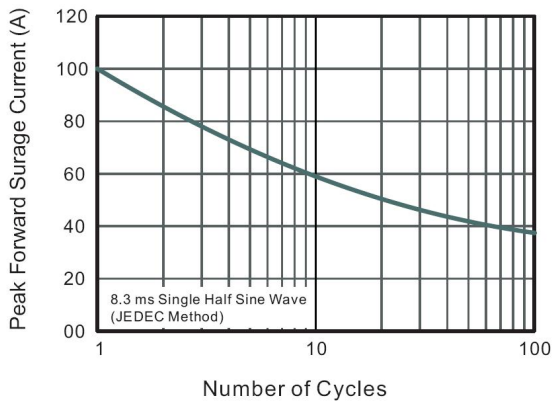
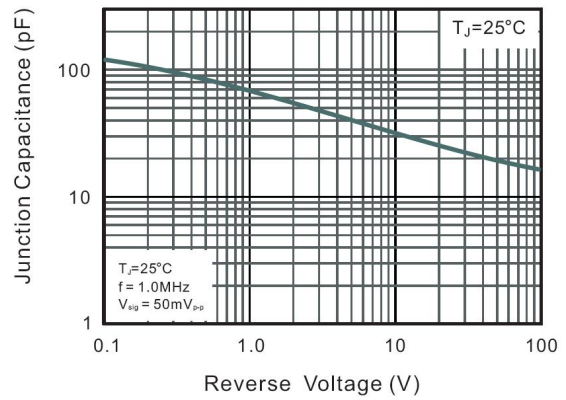
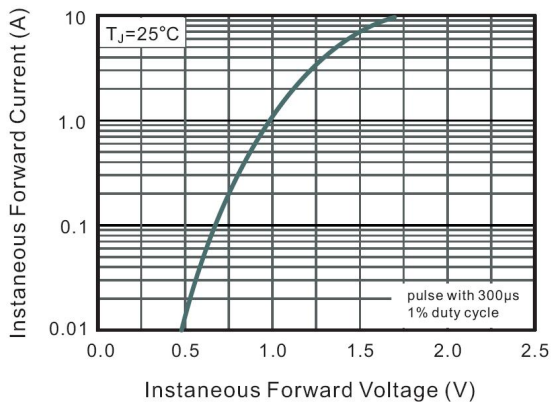
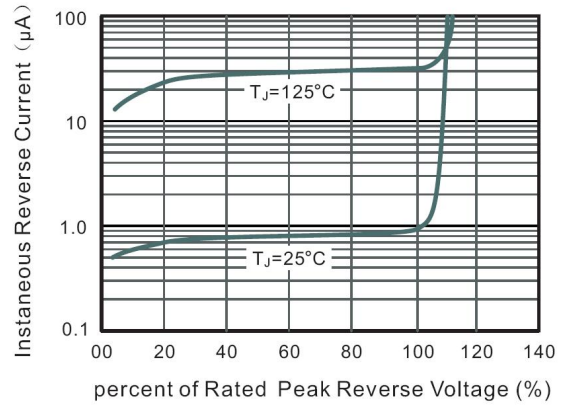
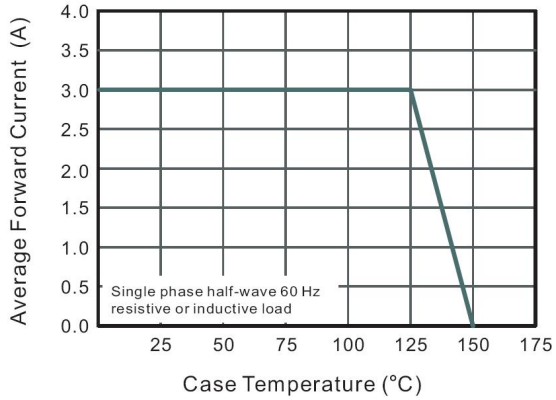
Note:

1) P.C.B. mounted with 1.0 X 1.0" (2.54 X 2.54 mm) copper pad areas.

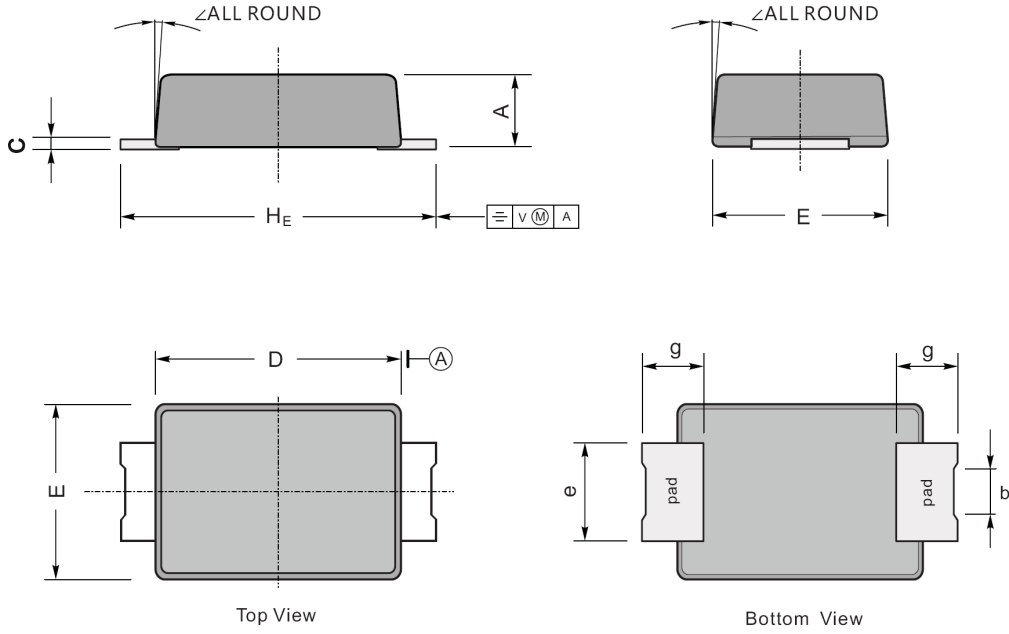
**电性能参数 / Electrical Characteristics(Ta=25°C)**

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating							单位 Unit
			RS3AF	RS3BF	RS3DF	RS3GF	RS3JF	RS3KF	RS3MF	
Maximum Instantaneous Forward Voltage	$V_F$	$I_F=3.0\text{A}$	1.3							V
Maximum DC Reverse Current at Rated DC Blocking Voltage	$I_R$	$T_a=25^\circ\text{C}$	5.0							$\mu\text{A}$
		$T_a=125^\circ\text{C}$	100							$\mu\text{A}$
Maximum Reverse Recovery Time	$t_{rr}$	$I_F=0.5\text{A}$ $I_R=1.0\text{A}$ $I_{rr}=0.25\text{A}$	150			250		500		ns

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

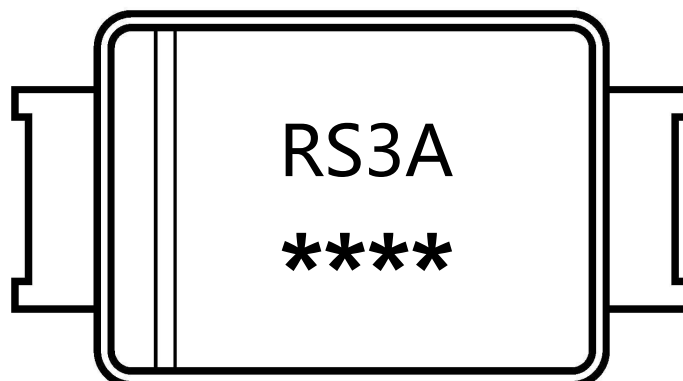


UNIT		A	C	D	E	e	g	H <sub>E</sub>	b	∠
mm	max	1.2	0.20	3.7	2.7	1.6	1.2	4.9	1.05	7°
	min	0.9	0.12	3.3	2.4	1.3	0.8	4.4	0.65	
mil	max	47	7.9	146	106	63	47	193	41	
	min	35	4.7	130	94	51	31	173	26	

印章说明 / Marking Instructions

Type number	Marking code
RS3AF	RS3A
RS3BF	RS3B
RS3DF	RS3D
RS3GF	RS3G
RS3JF	RS3J
RS3KF	RS3K
RS3MF	RS3M

印章说明 / Marking Instructions



说明：

RS3A：为型号代码

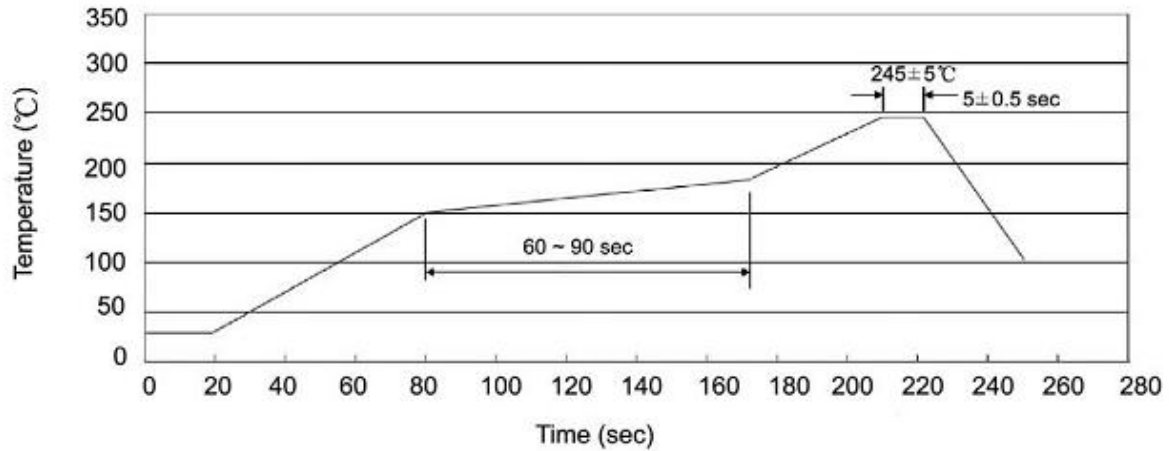
\*\*\*\*：为生产批号追溯码，第1个\*为年月代码，后面3个\*为当月小批号代码

Note:

RS3A：Product Type Code

\*\*\*\*：Lot No. Code ,The 1st \* means:YM Code ,The last 3 \* means:little Lot No Code

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度 150 ~ 180°C，时间 60 ~ 90sec；
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec；
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:150~180°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMAF	3000	5	15000	5	75000	7" ×11	185X180X105	390X385X205

**使用说明 / Notices**